MicroCoat Technologies

1316 Somerset Drive McKinney, TX 75070 www.m-coat.com Tel +1-972-678-4950 Fax +1-214-257-8890 Unparalleled in Polymer Coatings and Adhesives Technology TM



PRODUCT DATA SPECIFICATION

MCT SD0802 Series

A High Performance

Single Component, Very High Thermal Conductivity, Very Low Resistivity

Conductive Epoxy Interposer for Connecting Silicon Stacked Die Layers

MicroCoat Technologies announces the arrival of their new It is 100% solids, and posses' good handling and storage low resistivity - high thermal conductivity die-stacking properties. This silver-filled conductive adhesive is designed interconnect conductive adhesive MCT SD0802. Many to bond from IC to IC on Silicon with either gold or aluminum companies that are manufacturing stacked flash devices pads. It also bonds ICs and components to advanced have gone to very fine line dispensed conductive adhesive substrates such as ceramic, PBGAs, CSPs and array instead of wirebonding to make the connections from layer packages with virtually no bleed. Hydrophobic and stable at to layer. MCT has developed a magnificent solution. It can high temperatures, the adhesive produces a void-free line be a dispensed bead or using high speed jet dispensing of with excellent interfacial adhesion strength. This material is conductive adhesive, the material can be applied at 50 formulated to provide high cohesive energy, adhesive microns wide with no sag or slump to 16+ flash layers strength, and elongation at break. Operating temperature (tested to date) with a 7 day room temperature working life. range -55°C – 225°C; Short term to 300°C.

Besides the cost and space savings compared to wirebonding the conductive paths provide a ground-breaking method for helping to cool the device(s) with the high thermal conductivity of the epoxy acting as cooling fins. It is shown that a 32MB 3D stacked DRAM cache can reduce the cycles per memory access of a twothreaded RMS benchmark on average by 13% and as much as 55% while increasing the peak temperature by a negligible 0.08°C. Offdie BW and power are also reduced by 66% on average. It is also shown that a 3D floorplan of a high performance microprocessor can simultaneously reduce power 15% and increase performance 15% with a small 14°C increase in peak temperature. Voltage scaling can reach neutral thermals with a simultaneous 34% power reduction and 8% performance improvement. Bryan Black, et al, Intel Corporation.

This adhesive is a thixotropic silver filled conductive frozen adhesive capable of dispensed line widths of 50 microns.



SD0802G/5JS **Composition Properties** Filler Contents: 85+% Silver Viscosity: Thixotropic - Typ @ 10 RPM Brookfield HBT CP51 20-35 Kcps. 18-25 Kcps 18-25 Kcps 20-30 Kcps Thixo Ratio at above viscosity parameters ~1.89 - 2.30 Average Particle Size: .70 - 1.25 microns **Typical Cured Properties** Volume Resistivity: .00015 - .00008mohms (Dispensed)

Thermal Conductivity 11.0 - 11.9W/m-K CTE Alpha 1 ppm/°C 50 CTE Alpha 2 ppm/°C 200 Tg°C 117 Die Shear psi >8000 Shore "D" Hardness 75 - 80 Post Cure Ionics 883/5011.3.8.7 Cl=<6ppm, Na+=<3.3ppm, K+=<1.1ppm Teflon Flask 5 gm sample using 20-40 mesh, 50 gm DI H_2O , 100°C for 24 hours @65C = 5595 MPa, @25C = 5510 MPa, @150C = 925 MPa, @250C = 310 MPa Modulus:

<u>Processing Procedures:</u> Mixing: The material should be lightly stirred prior to use if used from a jar. Not required if in a syringe

Application: The material may be applied by Jet Spray, screen printing or syringe dispense

Curing: Cure at 150°C for 45 minutes. Optimum conditions will vary depending upon application and will need to be determined experimentally.

<u>Storage</u> MicroCoat should be stored in sealed containers away from heat or flames. It has a shelf life of 7-9 days at a storage temperature of 25° C, 3 months at -10° C or 6 months at -40° C.

DO NOT STORE AT TEMPERATURE BELOW -40°C.

Material *may* be returned to refrigerator/freezer after using partial syringes or jars if within the shelf life window.

Packaging: 3cc, and 10cc syringes Shipped in Freeze Packs next day delivery only

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